

N- and P-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY							
	V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)				
N-Channel	60	1.0 at V _{GS} = 10 V	0.55				
	60	1.4 at V _{GS} = 4.5 V	0.37				
P-Channel	- 60	2.5 at V _{GS} = - 10 V	- 0.3				
		3 at V _{GS} = - 4.5 V	- 0.2				

FEATURES

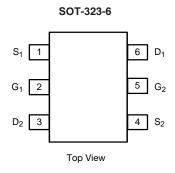
- DT-Trench Power MOSFET
- 100 % R_g tested
- PWM Optimized
- Compliant to RoHS Directive 2002/95/EC

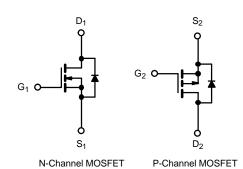


RoHS

APPLICATIONS

- LED Inverter Circuits
- DC/DC Conversion Circuits
- Motor drives
- · Low power load switch





ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)							
Parameter		Symbol	N-Channel	P-Channel	Unit		
Drain-Source Voltage		V_{DS}	60	- 60	V		
Gate-Source Voltage		V_{GS}	± 20]		
Continuous Drain Current (T _J = 150 °C) ^a	T _C = 25 °C	I _D	0.55	- 0.3			
	T _C = 70 °C		0.42	- 0.21			
Pulsed Drain Current ^b		I _{DM}	1.7	- 0.9	Α		
Continuous Source Current (Diode Conduction) ^a		I _S	0.55	- 0.3			
Maximum Power Dissipation ^a	T _C = 25 °C	- P _D	0.73	0.3	W		
	T _C = 70 °C		0.47	0.192			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 t	o 150	°C		

Notes:

- a. Surface mounted on FR4 board.
- b. Pulse width limited by maximum junction temperature.



V _{DS} = 60 V, V _{GS} = 0 V V _{CS} V _{CS}	Parameter	Symbol	Test Conditions		Min.	Тур.	Max.	Unit	
Drain-Source Breakdown Voltage V _{GS} V _{GS} = 0 V, I _D = -10 μA P-Ch -60	Static								
Vas	Drain Source Breakdown Voltage	V	$V_{GS} = 0 \text{ V}, I_{D} = 10 \mu\text{A}$	N-Ch	60				
Gate Inreshold voltage VGS(th) VDS = VGS, ID = -250 μA P-Ch -1 -3.0	Dialii-Source Breakdown Voltage	V DS	$V_{GS} = 0 \text{ V, I}_{D} = -10 \mu\text{A}$	P-Ch	- 60			V	
Sate-Body Leakage IGSS VDS = 0 V, VGS = ± 10 V P-Ch ± 100	Cata Threshold Voltage	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	N-Ch	1		3.0	V	
Vos = 0 V, Vos = ± 10 V P-Ch ± 100	Gate i nresnoid Voltage	VGS(th)	V _{DS} = V _{GS} , I _D = - 250 μA	P-Ch	- 1		- 3.0		
Vas = 60 V, Vas = 0 V	Gate-Body Leakage	loce	V = 0 V V = + 10 V	N-Ch			± 100		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	can load action	433	V _{DS} = 0 V, V _{GS} = ± 10 V	P-Ch			± 100	nA	
V _{DS} = 48 V, V _{GS} = 0 V, T _J = 85 °C V-Ch			V _{DS} = 60 V, V _{GS} = 0 V	N-Ch			1	<u>—</u> иА	
V _{DS} = 48 V, V _{GS} = 0 V, T _J = 85 °C V _{DS} = 48 V, V _{GS} = 0 V, T _J = 85 °C V _{DS} = 48 V, V _{GS} = 0 V, T _J = 85 °C V _{DS} = 45 V _{DS} = 10 V, V _{GS} = 4.5 V _{DS} = 10 V, V _{GS} = 4.5 V _{DS} = 10 V, V _{GS} = 4.5 V _{DS} = 0.2 A _{DS} = 0.0 V	Zana Cata Valtana Duain Comunat		V _{DS} = - 60 V, V _{GS} = 0 V	P-Ch			- 1		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	zero Gate Voltage Drain Current	DSS	V _{DS} = 48 V, V _{GS} = 0 V, T _J = 85 °C	N-Ch			10		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$				P-Ch			- 10	1	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	Drain-Source On-State	ln()	V _{DS} = 10 V, V _{GS} = 4.5 V	N-Ch	0.55				
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		יט(on)	V _{DS} = - 10 V, V _{GS} = - 4.5 V	P-Ch	- 0.3			Α	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			$V_{GS} = 4.5 \text{ V}, I_D = 0.2 \text{ A}$	N-Ch		1.4	2.0		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			V _{GS} = - 4.5 V, I _D = - 0.1 A	P-Ch		3.0	4.0	Ω	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		В		N-Ch		1.0	1.5		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		H _{DS(on)}	V _{GS} = - 10 V, I _D = - 0.1 A	P-Ch		2.5	3.0		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Forward Transconductance ^a	g _{fs}		N-Ch		195		ms	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			V _{DS} = - 10 V, I _D = - 0.1A	P-Ch		150			
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Diode Forward Voltage ^a		I _S = 0.2 A, V _{GS} = 0 V	N-Ch		0.8	1.2	V	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		V SD	I _S = - 0.1 A, V _{GS} = 0 V	P-Ch		- 0.8	- 1.2	ľ	
	Dynamic ^b								
	Total Gate Charge	0.		N-Ch		1.5			
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Total Gate Charge	Q g		P-Ch		1.6		nC	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Gate-Source Charge	Q _{ma}	V _{DS} = 30 V, V _{GS} = 4.3 V, I _D = 0.2 A	N-Ch		0.3			
	- Cate Course Charge	gs				0.36			
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Gate-Drain Charge	Q_{nd}	$V_{DS} = -30 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -0.1 \text{ A}$						
		gu							
Output Capacitance $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ $P-Ch$ 49 Reverse Transfer Capacitance C_{rss} $V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ $N-Ch$ $N-Ch$ $N-Ch$ Turn-On Time ^c t_{ON} $V_{DD} = 30 \text{ V}, R_L = 100 \Omega$ $N-Ch$ $N-Ch$ $N-Ch$ $I_D \cong 0.2 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$ $N-Ch$ $N-Ch$ $N-Ch$ $I_D \cong 0.2 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$ $N-Ch$ $N-Ch$ $N-Ch$ $I_D \cong 0.2 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$ $N-Ch$ $N-Ch$ $N-Ch$ $I_D \cong 0.2 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 10 \Omega$ $N-Ch$ $N-Ch$ $N-Ch$	Input Capacitance	C _{iss}	N-Channel					-	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			$V_{P0} = 30 \text{ V} V_{P0} = 0 \text{ V} f = 1 \text{ MHz}$					-	
	Output Capacitance	Coss	, do ,	-		-		pF	
Reverse Transfer Capacitance C_{rss} DS SS SS SS SS SS SS SS		C _{rss}	r-Charner					4	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$					1	
Turn-On Time ^c t_{ON} $V_{DD} = 30 \text{ V}, R_L = 100 \Omega$ $I_D \cong 0.2 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$ P-Ch $I_D \cong 0.2 \text{ A}, V_{GEN} = 100 \Omega$ I_{OFF} I_{OFF			N Channal				-		
$I_D\cong 0.2 \text{ A, } V_{\text{GEN}}=10 \text{ V, } R_g=1\Omega \qquad \qquad \text{P-Ch} \qquad \qquad 3$ $\begin{array}{c ccccccccccccccccccccccccccccccccccc$	Turn-On Time ^c	ton				6.5			
Turn-Off Time ^c t_{OFF} $V_{DD} = -30 \text{ V, } R_L = 100 \Omega$		UN		P-Ch		3			
	Turn-Off Time ^c			N-Ch		13		ns	
$I_D \cong -0.1 \text{ A, V}_{GEN} = -10 \text{ V, R}_g = 1 \Omega$ P-Ch 13		t _{OFF}		P-Ch			1	1	

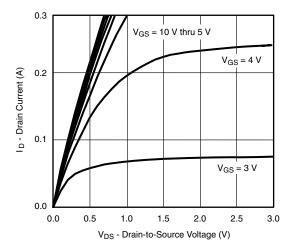
Notes:

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.
- c. Switching time is essentially independent of operating temperature.

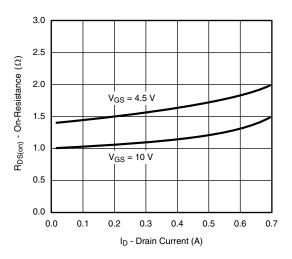
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



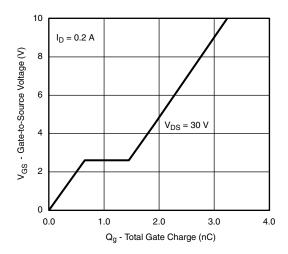
N-CHANNEL TYPICAL CHARACTERISTICS ($T_A = 25 \, ^{\circ}C$, unless otherwise noted)



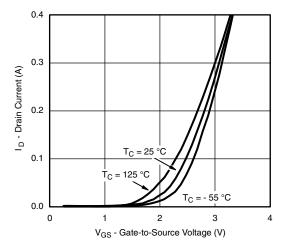
Output Characteristics



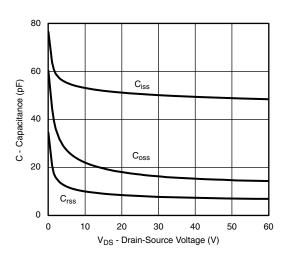
On-Resistance vs. Drain Current



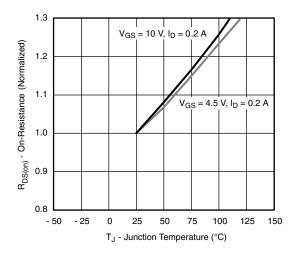
Gate Charge



Transfer Characteristics Curves vs. Temperature



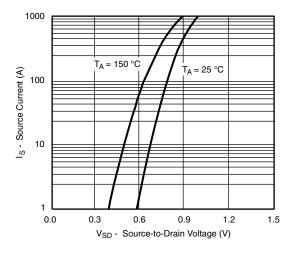
Capacitance



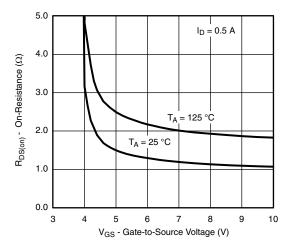
On-Resistance vs. Junction Temperature



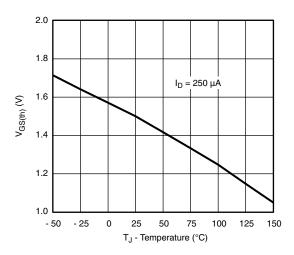
N-CHANNEL TYPICAL CHARACTERISTICS ($T_A = 25 \, ^{\circ}C$, unless otherwise noted)



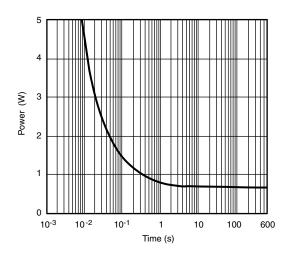
Source-Drain Diode Forward Voltage



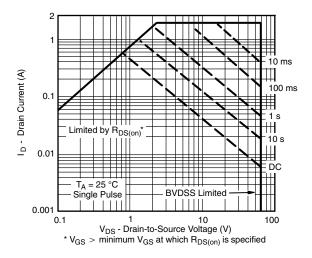
 $R_{DS(on)}\, vs.\, V_{GS}\, vs.\, Temperature$



Threshold Voltage



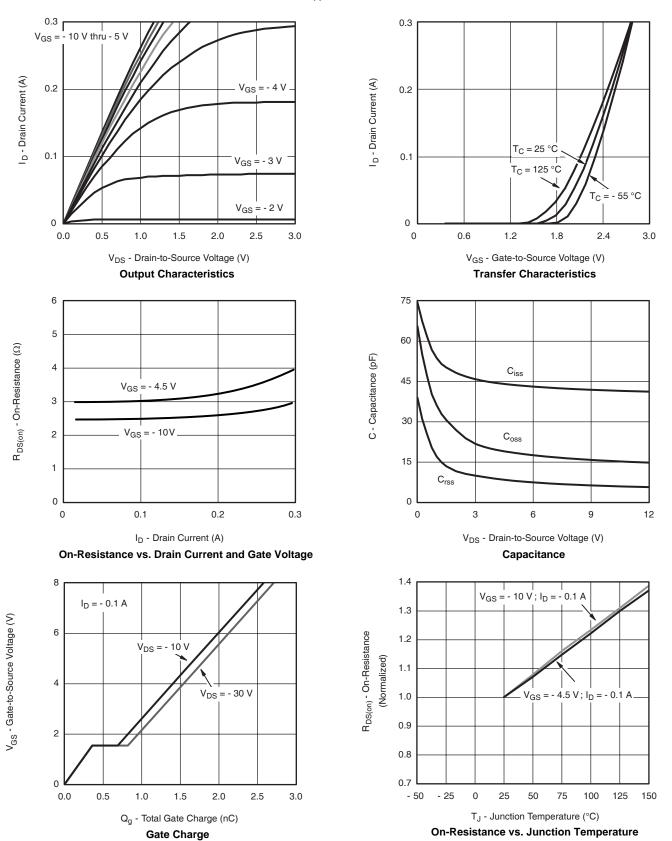
Single Pulse Power



Safe Operating Area

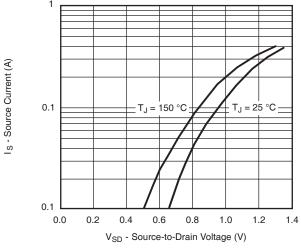


P-CHANNEL TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)

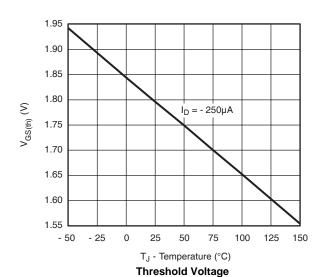




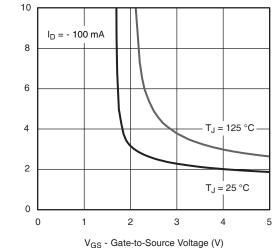
P-CHANNEL TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)



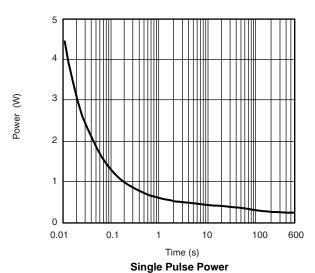
Source-Drain Diode Forward Voltage

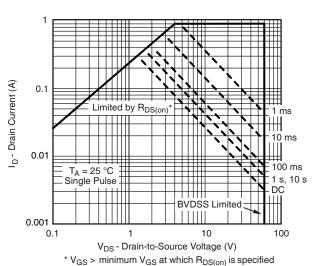


 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - On-Resistance (Ω)



On-Resistance vs. Gate-to-Source Voltage

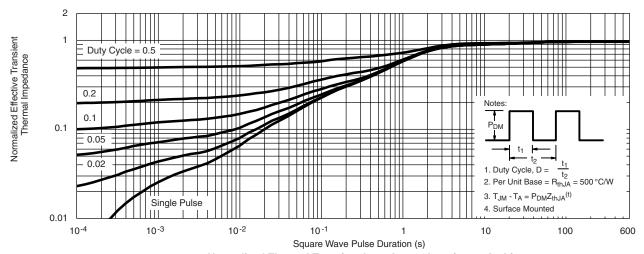




Safe Operating Area, Junction-to-Ambient



N- OR P-CHANNEL TYPICAL CHARACTERISTICS ($T_A = 25~^{\circ}C$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient





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